



Title of Change:	Initial PCN for wire change from gold to copper, mold compound change and part number change.											
Proposed first ship date:	9 October 2015											
Contact information:	Contact your local ON Semiconductor Sales Office or < Yasuhiro Igarashi @onsemi.com >											
Samples:	Contact your local ON Semiconductor Sales Office.											
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>											
Change Identification:	Part	Affected products will be identified with new part number (changing suffix to "-W").										
		<table border="1"> <thead> <tr> <th>PART_ID</th> <th>New Part_ID</th> </tr> </thead> <tbody> <tr> <td>VEC2315-TL-H</td> <td>VEC2315-TL-W</td> </tr> <tr> <td>VEC2415-TL-E</td> <td>VEC2415-TL-W</td> </tr> <tr> <td>VEC2616-TL-H</td> <td>VEC2616-TL-W</td> </tr> <tr> <td>VEC2616-TL-H-Z</td> <td>VEC2616-TL-W-Z</td> </tr> </tbody> </table>	PART_ID	New Part_ID	VEC2315-TL-H	VEC2315-TL-W	VEC2415-TL-E	VEC2415-TL-W	VEC2616-TL-H	VEC2616-TL-W	VEC2616-TL-H-Z	VEC2616-TL-W-Z
PART_ID	New Part_ID											
VEC2315-TL-H	VEC2315-TL-W											
VEC2415-TL-E	VEC2415-TL-W											
VEC2616-TL-H	VEC2616-TL-W											
VEC2616-TL-H-Z	VEC2616-TL-W-Z											
Change category(s):	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____											
Sites Affected:	Site 1	Site 2										
<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	ON Shenzhen, China											
Description and Purpose:												
<p>This is an Initial Process Change Notification to announce the contents below.</p> <ol style="list-style-type: none"> 1) Changing wire material from gold to copper 2) Changing part number from XXXXXXX-TL-E, XXXXXXX-TL-H and XXXXXXX-TL-H-Z to XXXXXXX-TL-W and XXXXXXX-TL-W-Z. 3) Changing mold compound from halide to halide free. 												
Qualification Plan:												
Estimated date for qualification completion: 18 June 2015												
Test	Conditions	Results										
Steady State Operating Life	Tj=150degC	1000 hrs.										
High Temperature Reverse Bias	Ta=150degC,VR=max	1000 hrs.										
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs.										
Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles										
Pressure Cooker	Ta=121degC,2.03×10 ⁵ Pa,100%	50 hrs.										
High Temperature Storage	Ta=150degC	1000 hrs.										
Resistance to Soldering heat(Reflow)	Solder Temp.:260degC±5degC	10s										
Solderability	Solder Temp.: 245degC±5degC	5 s										



List of Affected Standard Parts:

VEC2315-TL-H
VEC2415-TL-E
VEC2616-TL-H
VEC2616-TL-H-Z